Triacs BT139X series

### **GENERAL DESCRIPTION**

### **QUICK REFERENCE DATA**

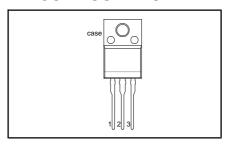
Passivated triacs in a full pack, plastic envelope, intended for use in applications requiring high bidirectional transient and blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.

SYMBOL	PARAMETER	MAX.	MAX.	UNIT
	BT139X- BT139X- BT139X-	600 600F 600G	800	
$V_{DRM}$	Repetitive peak off-state voltages	600	800	V
I <sub>T(RMS)</sub> I <sub>TSM</sub>	RMS on-state current Non-repetitive peak on-state current	16 140	16 140	A A

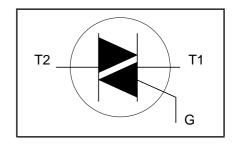
### **PINNING - SOT186A**

PIN	DESCRIPTION					
1	main terminal 1					
2	main terminal 2					
3	gate					
case	isolated					

### **PIN CONFIGURATION**



### **SYMBOL**



### **LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT
$V_{DRM}$	Repetitive peak off-state voltages		-	<b>-600</b> 600 <sup>1</sup>	<b>-800</b> 800	V
$I_{T(RMS)} \\ I_{TSM}$	RMS on-state current Non-repetitive peak on-state current	full sine wave; $T_{hs} \le 38 ^{\circ}\text{C}$ full sine wave; $T_{j} = 25 ^{\circ}\text{C}$ prior to surge	-	16		A
		t = 20 ms t = 16.7 ms	-	14	-	A
l²t dl <sub>⊤</sub> /dt	l <sup>2</sup> t for fusing Repetitive rate of rise of on-state current after	t = 10.7  ms t = 10  ms $I_{TM} = 20 \text{ A}; I_G = 0.2 \text{ A};$ $dI_G/dt = 0.2 \text{ A}/\mu\text{s}$	- -	15 98		A A <sup>2</sup> s
	triggering	T2+ G+ T2+ G- T2- G- T2- G+	- - -	50 50 50 10	0 0	Α/μs Α/μs Α/μs Α/μs
I <sub>GM</sub> V <sub>GM</sub> P <sub>GM</sub>	Peak gate current Peak gate voltage Peak gate power		- - -	2 5 5		V W
P <sub>G(AV)</sub> T <sub>stg</sub> T <sub>j</sub>	Average gate power Storage temperature Operating junction temperature	over any 20 ms period	-40 -	0. 15 12	50	ů Ĉ W

<sup>1</sup> Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15  $A/\mu s$ .

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# **ISOLATION LIMITING VALUE & CHARACTERISTIC**

 $T_{hs}$  = 25  $^{\circ}$ C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>isol</sub>	R.M.S. isolation voltage from all three terminals to external heatsink	f = 50-60 Hz; sinusoidal waveform; R.H. ≤ 65%; clean and dustfree	-	1	2500	V
C <sub>isol</sub>	Capacitance from T2 to external heatsink	f = 1 MHz	-	10	-	pF

# THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R <sub>th j-hs</sub>	Thermal resistance junction to heatsink	full or half cycle with heatsink compound without heatsink compound	-	-	4.0 5.5	K/W K/W
R <sub>th j-a</sub>	Thermal resistance junction to ambient	in free air	-	55	-	K/W

# STATIC CHARACTERISTICS

 $T_i = 25$  °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.			UNIT
	Cata trigger ourrent	BT139X-				F	G	
I <sub>GT</sub>	Gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$ T2+ G+	-	5	35	25	50	mA
		T2+ G- T2- G-	-	8 10	35 35	25 25	50 50	mA mA
١.	Latabia a a comant	T2- G+	-	22	70	70	100	mA
I <sub>L</sub>	Latching current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$ T2+ G+	-	7	40	40	60	mA
		T2+ G- T2- G-	-	20 8	60 40	60 40	90 60	mA mA
l.		T2- G+	-	10	60	60	90	mA
I <sub>H</sub>	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	6	30	30	60	mA
$V_{T}$	On-state voltage Gate trigger voltage	$I_T = 20 \text{ A}$ $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$	-	1.2 0.7		1.6 1.5		V
V GT	Oate trigger voltage	$V_D = 400 \text{ V}; I_T = 0.1 \text{ A};$	0.25	0.4		-		ľ v l
I <sub>D</sub>	Off-state leakage current	$ T_j = 125 °C $ $ V_D = V_{DRM(max)}; $ $ T_j = 125 °C $	-	0.1		0.5		mA

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# **DYNAMIC CHARACTERISTICS**

 $T_i = 25$  °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS		MIN.		TYP.	MAX.	UNIT
dV <sub>D</sub> /dt	Critical rate of rise of off-state voltage	<b>BT139X-</b> $V_{DM} = 67\% V_{DRM(max)};$ $T_i = 125  ^{\circ}C;$ exponential	 100	<b>F</b> 50	<b>G</b> 200	250	-	V/μs
dV <sub>com</sub> /dt	Critical rate of change of	waveform; gate open circuit V <sub>DM</sub> = 400 V; T <sub>j</sub> = 95 °C; I <sub>T(RMS)</sub> = 16 A; dI <sub>com</sub> /dt = 7.2 A/ms; gate	-	-	10	20	-	V/μs
t <sub>gt</sub>	Gate controlled turn-on time	open circuit $I_{TM} = 20 \text{ A}; V_D = V_{DRM(max)}; I_G = 0.1 \text{ A}; dI_G/dt = 5 \text{ A}/\mu s$	-	-	-	2	-	μs

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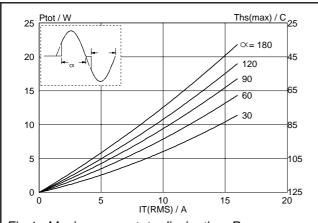


Fig.1. Maximum on-state dissipation,  $P_{tot}$ , versus rms on-state current,  $I_{T(RMS)}$ , where  $\alpha =$  conduction angle.

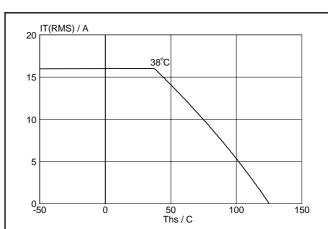


Fig.4. Maximum permissible rms current  $I_{\text{T(RMS)}}$ , versus heatsink temperature  $T_{\text{hs}}$ .

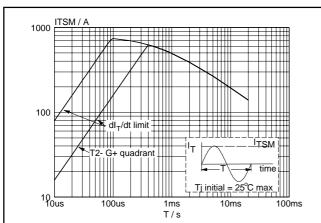


Fig.2. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus pulse width  $t_p$ , for sinusoidal currents,  $t_p \le 20$ ms.

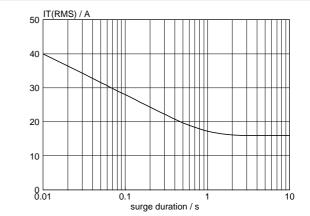


Fig.5. Maximum permissible repetitive rms on-state current  $I_{T(RMS)}$ , versus surge duration, for sinusoidal currents, f = 50 Hz;  $T_{hs} \le 38$  °C.

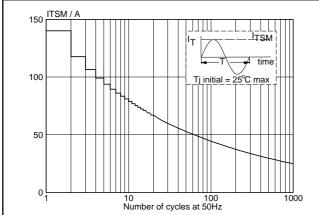


Fig.3. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus number of cycles, for sinusoidal currents, f = 50 Hz.

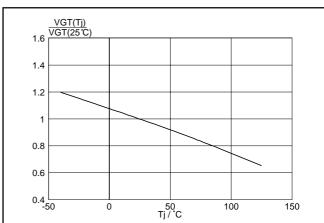
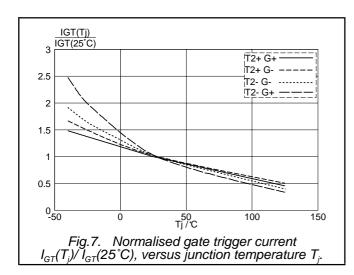
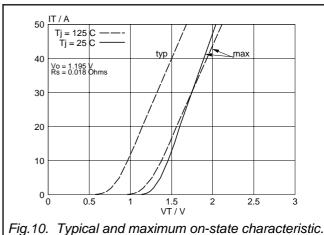
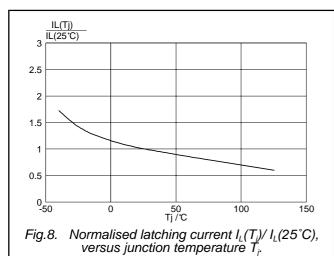


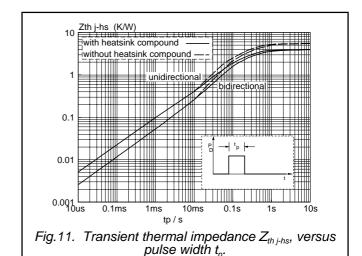
Fig.6. Normalised gate trigger voltage  $V_{GT}(T_j)/V_{GT}(25^{\circ}C)$ , versus junction temperature  $T_j$ .

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IH(Tj) 3 IH(25°C) 0.5 0 -50 50 Tj /℃ 100 150 Fig.9. Normalised holding current  $I_H(T_i)/I_H(25^{\circ}\text{C})$ , versus junction temperature  $T_j$ .

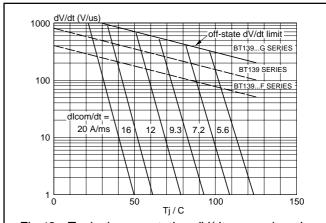
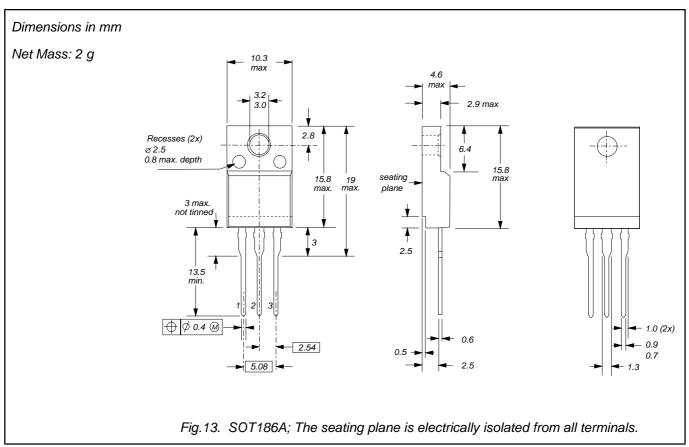


Fig.12. Typical commutation dV/dt versus junction temperature, parameter commutation dl<sub>T</sub>/dt. The triac should commutate when the dV/dt is below the value on the appropriate curve for pre-commutation  $dI_{\tau}/dt$ .

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# **MECHANICAL DATA**



- Notes
  1. Refer to mounting instructions for F-pack envelopes.
  2. Epoxy meets UL94 V0 at 1/8".

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### **DEFINITIONS**

DATA SHEET STATUS							
DATA SHEET STATUS <sup>2</sup>	PRODUCT STATUS <sup>3</sup>	DEFINITIONS					
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice					
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in ordere to improve the design and supply the best possible product					
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A					

### Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

### **Application information**

Where application information is given, it is advisory and does not form part of the specification.

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<sup>2</sup> Please consult the most recently issued datasheet before initiating or completing a design.

**<sup>3</sup>** The product status of the device(s) described in this datasheet may have changed since this datasheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.